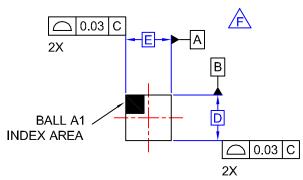
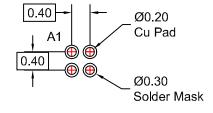


WLCSP4 0.82x0.82x0.586

CASE 567QD ISSUE O

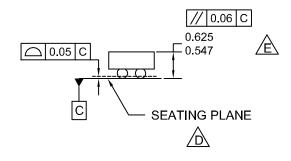
DATE 31 OCT 2016

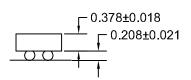




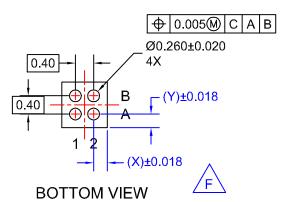
TOP VIEW

RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.

DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP4 0.82x0.82x0.586		PAGE 1 OF 1

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